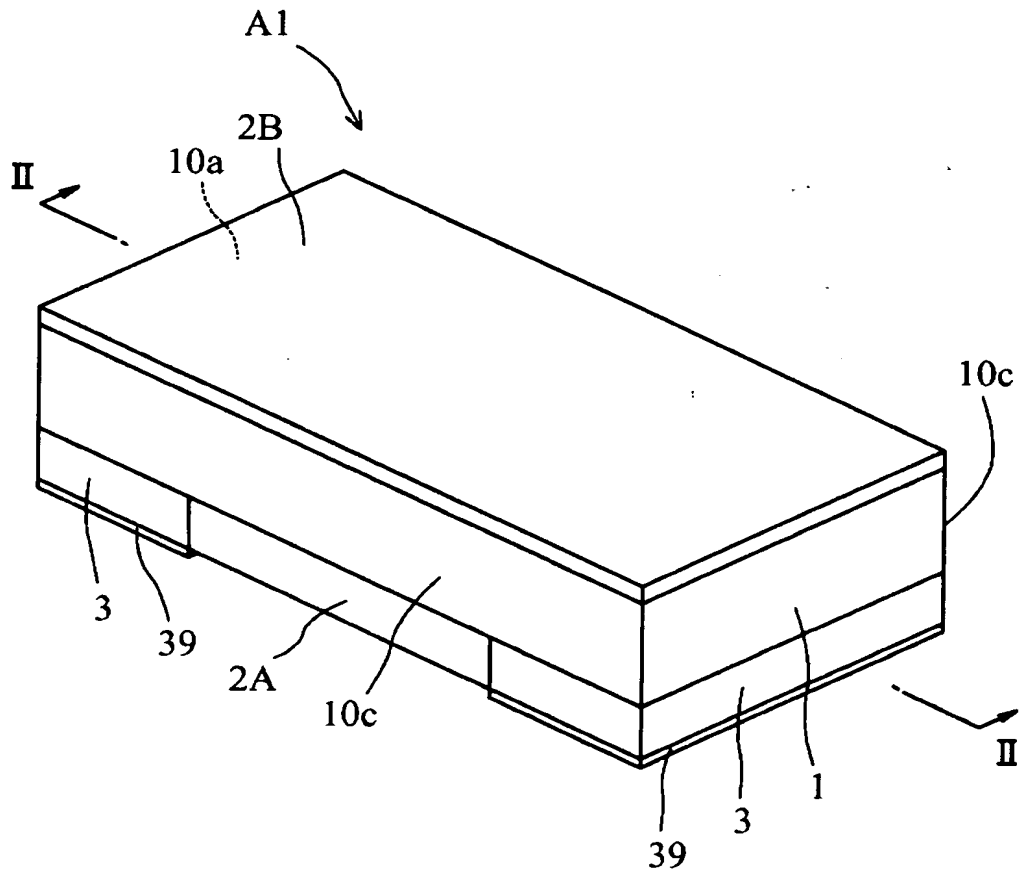


FIG.1



10/552301

FIG.2

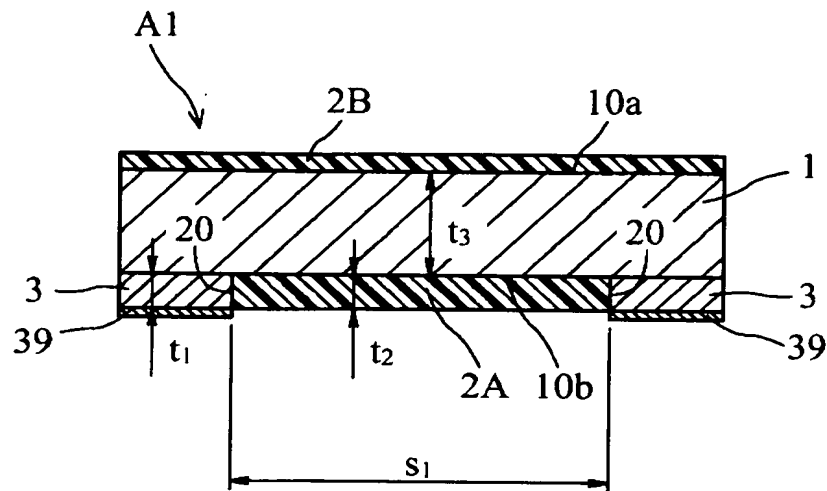


FIG.3A

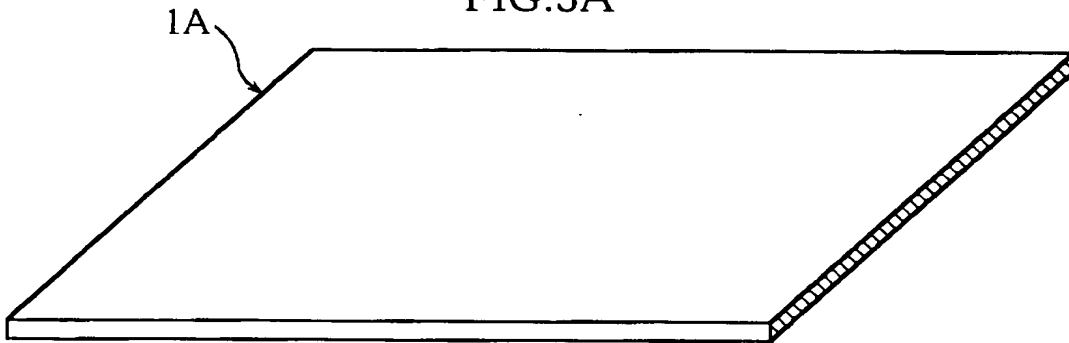


FIG.3B

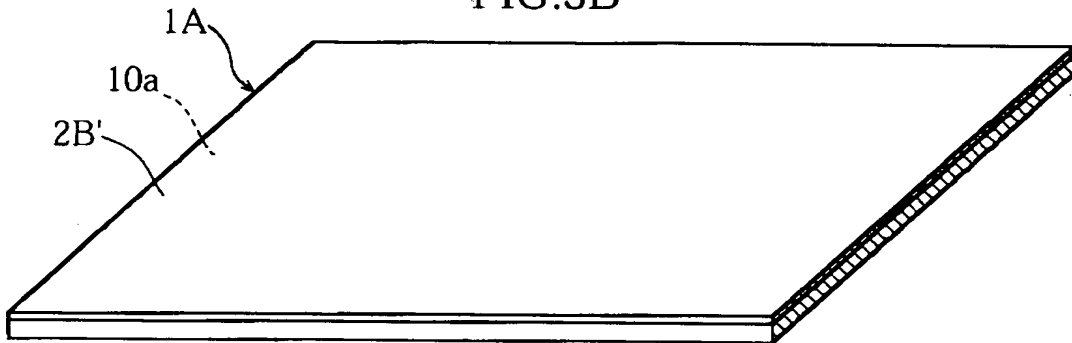
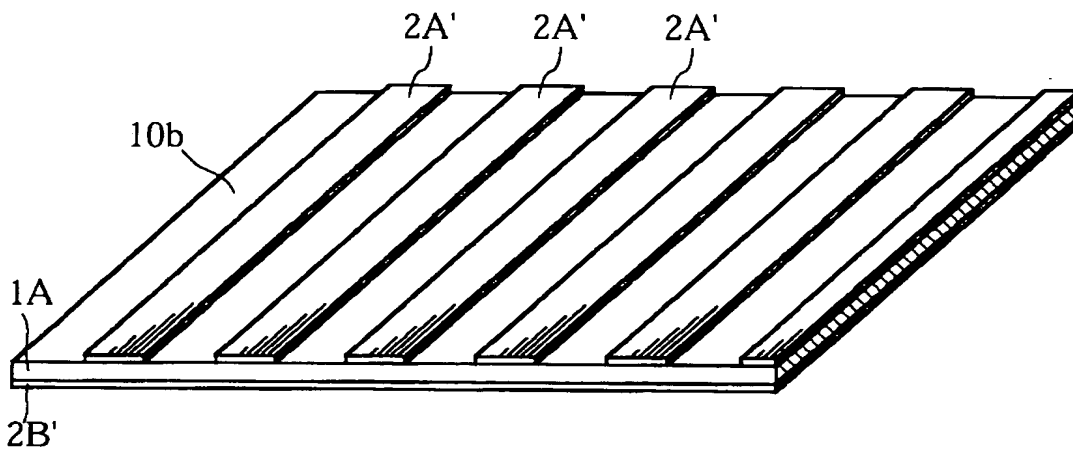


FIG.3C



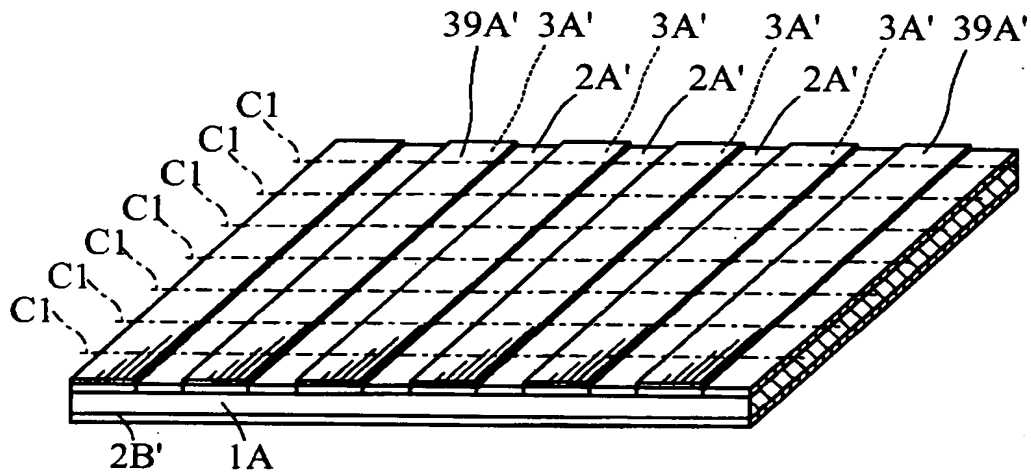
A perspective view of a multi-layered structure 1A. It consists of a base layer 2B' and a top layer 2A' with a series of parallel ridges 3A' and grooves 39A'.

FIG. 4B

FIG. 4B is a perspective view of a substrate 1A. The substrate 1A is a rectangular plate with a top layer 1A and a bottom layer 2B'. A grid of conductive strips is formed on the top layer 1A. The strips are arranged in two sets: 2A' (vertical strips) and 2B' (horizontal strips). The strips are connected by a conductive layer 39. The strips are separated by insulating material 3. A detailed view A1 shows a cross-section of the strips 2A and 2B, which are connected by a conductive layer 39. The strips are separated by insulating material 3. The substrate 1A has a top layer 1A and a bottom layer 2B'.

10/552301

FIG. 5



10/552301

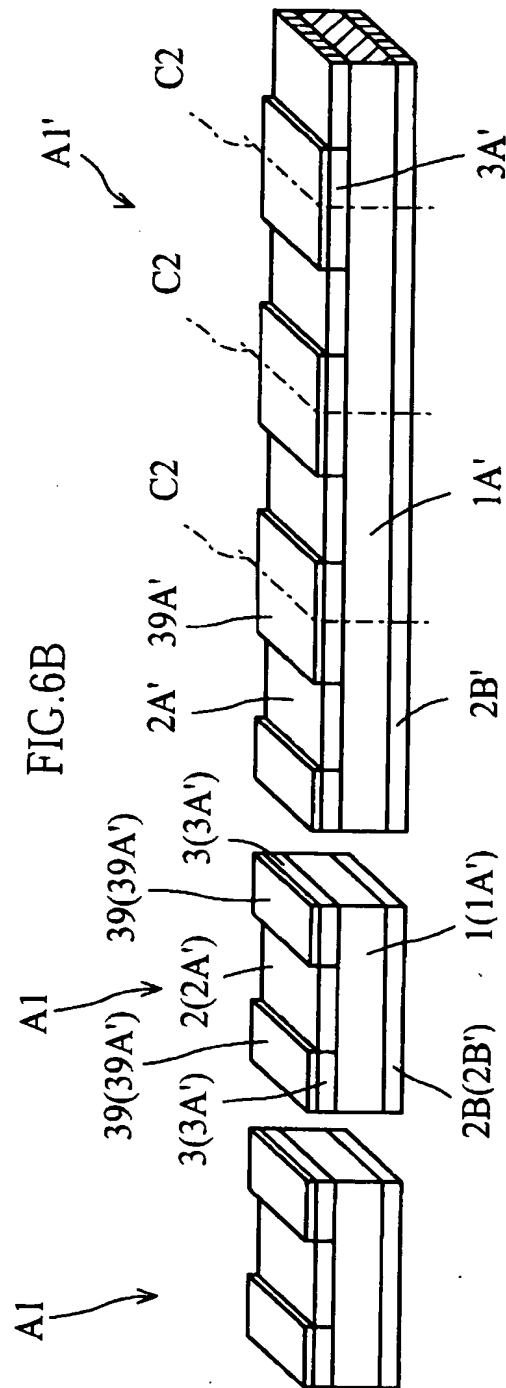
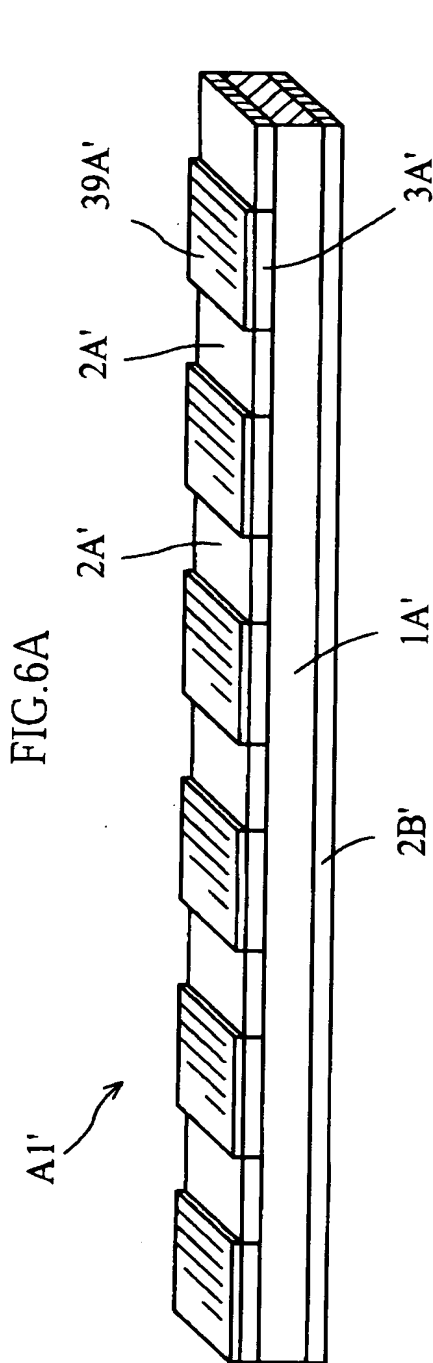


FIG. 7

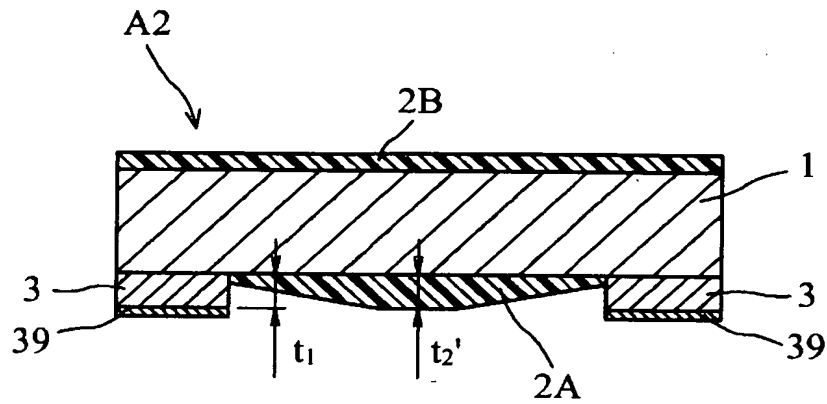


FIG.8A

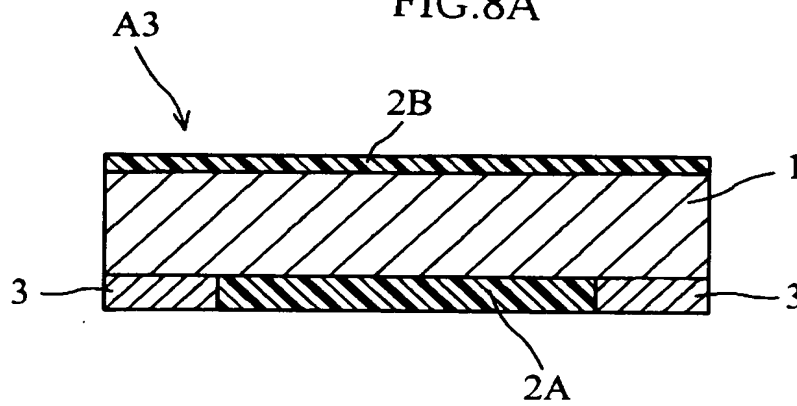


FIG.8B

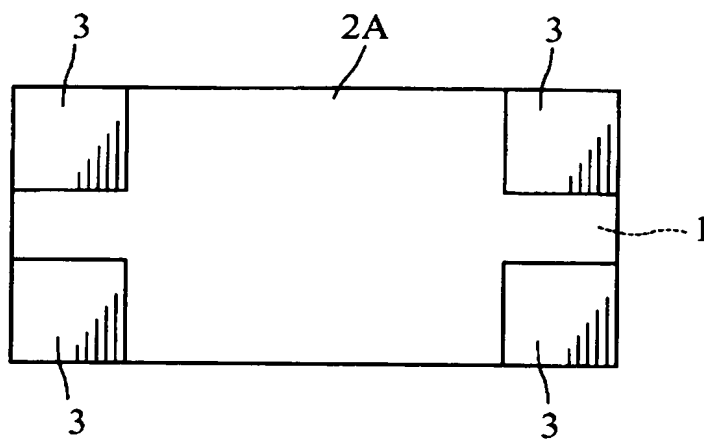
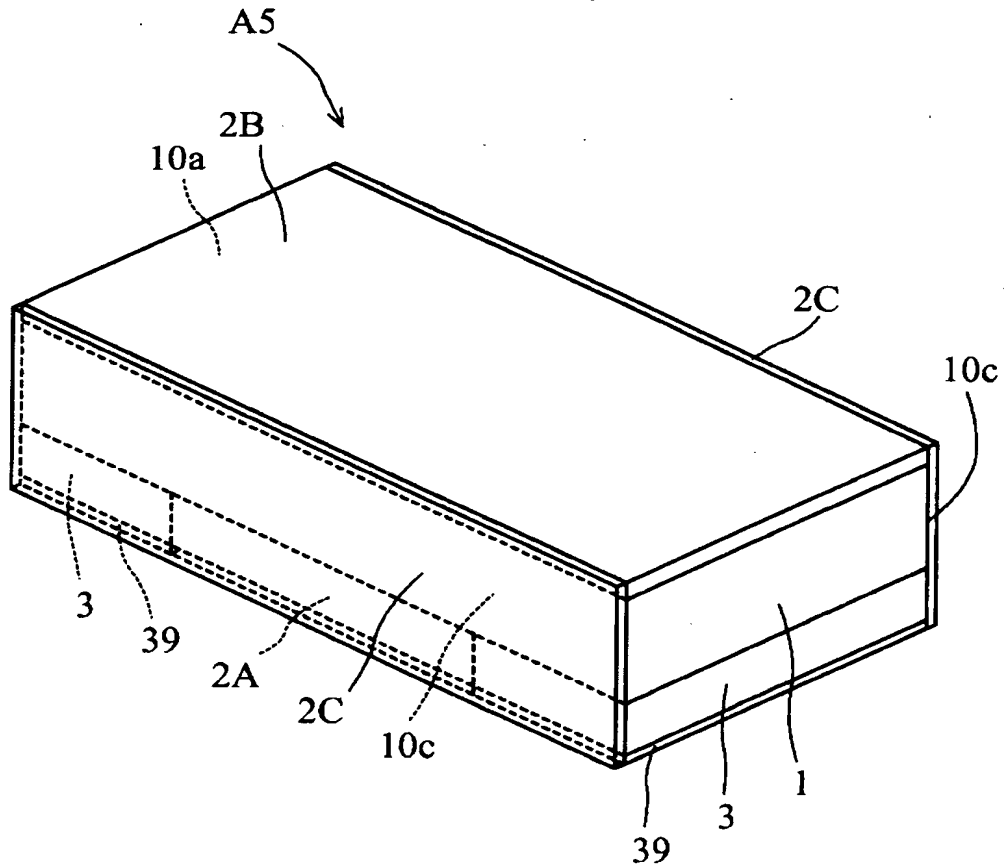






FIG.10



10/552301

FIG.11  
PRIOR ART

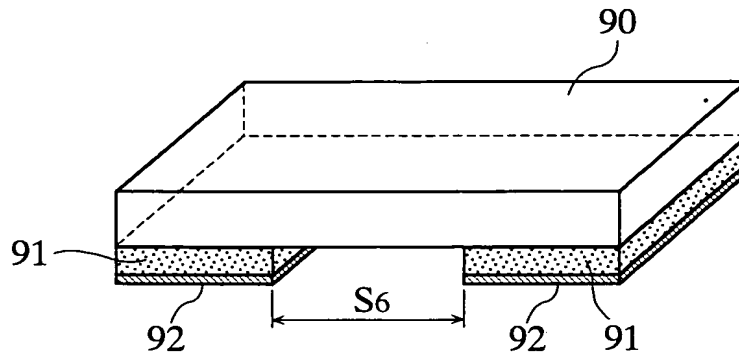


FIG.12  
PRIOR ART

